MAX.

600D

600E

600F

600

16

140

UNIT

V

A

А

Three quadrant triacs guaranteed commutation

BTA216 series D, E and F

GENERAL DESCRIPTION

Passivated guaranteed commutation triacs in a plastic envelope intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

PINNING - TO220AB

PIN CONFIGURATION

 V_{DRM}

T(RMS)

I_{TSM}

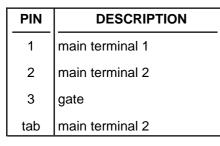
SYMBOL

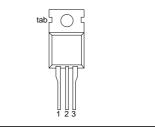
SYMBOL

BTA216-

BTA216-

BTA216-





QUICK REFERENCE DATA

voltages

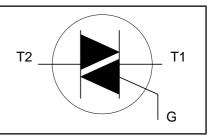
current

PARAMETER

Repetitive peak off-state

Non-repetitive peak on-state

RMŠ on-state current



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{DRM}	Repetitive peak off-state voltages		-	600 ¹	V
I _{T(RMS)}	RMS on-state current	full sine wave; $T_{mb} \le 99 \degree C$	-	16	A
I _{TSM}	Non-repetitive peak on-state current	full sine wave; $T_j = 25 °C$ prior to surge			
		t = 20 ms t = 16.7 ms	-	140 150	A A
l ² t	I ² t for fusing	t = 10 ms	-	98	A ² s
dl _⊤ /dt	Repetitive rate of rise of on-state current after	$I_{TM} = 20 \text{ A}; I_G = 0.2 \text{ A}; dI_G/dt = 0.2 \text{ A}/\mu s$	-	100	A/μs
L	triggering Peak gate current		_	2	A
I _{GM} Р _{GM}	Peak gate power		-	5	Ŵ
$P_{G(AV)}$	Average gate power	over any 20 ms period	-	0.5	Ŵ
T _{stg} T _j	Storage temperature Operating junction temperature	F 5119 G	-40 -	150 125	°C °C

¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 15 $A/\mu s$.

BTA216 series D, E and F

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-mb} R _{th j-a}	Thermal resistance junction to mounting base Thermal resistance junction to ambient	full cycle half cycle in free air		- - 60	1.2 1.7 -	K/W K/W K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT	
		BTA216-		D	E	F	
I _{GT}	Gate trigger current ²	$V_{\rm D} = 12 \text{ V}; I_{\rm T} = 0.1 \text{ A}$					
		T2+ G+	-	5	10	25	mA
		T2+ G-	-	5 5 5	10	25	mA
		T2- G-	-	5	10	25	mA
l I _L	Latching current	$V_{\rm D} = 12 \text{ V}; I_{\rm GT} = 0.1 \text{ A}$					
		T2+ G+	-	15	25	30	mA
		T2+ G-	-	25	30	40	mA
		T2- G-	-	25	30	40	mA
I _H	Holding current	V _D = 12 V; I _{GT} = 0.1 A	-	15	25	30	mA
			D, E, F				
V _T	On-state voltage	I _τ = 20 A	-		1.5		V
V _{GT}	Gate trigger voltage	$\dot{V}_{\rm D} = 12 \text{ V}; \text{ I}_{\rm T} = 0.1 \text{ A}$	-		1.5		V
		$V_{\rm D} = 400 \text{ V}; I_{\rm T} = 0.1 \text{ A};$	0.25		-		V
.	Official states and states and states	$T_{j} = 125 \ ^{\circ}C$			0.5		
I _D	Off-state leakage current	$V_D = V_{DRM(max)}; T_j = 125 °C$	-		0.5		mA

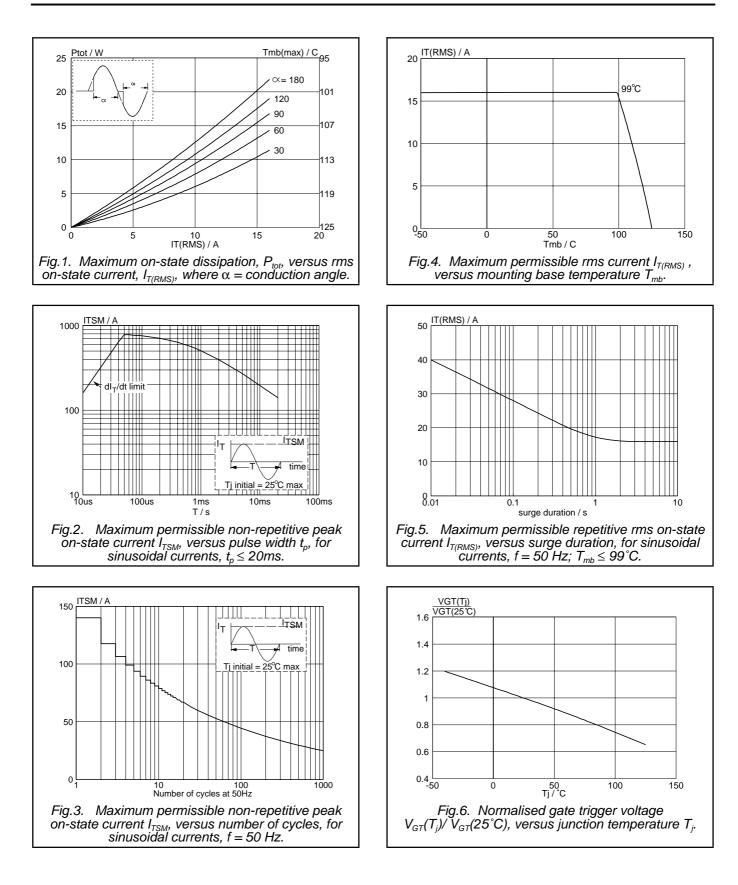
DYNAMIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS		MIN.		MAX.	UNIT
		BTA216-	D	E	F		
dV _D /dt	Critical rate of rise of off-state voltage	$V_{DM} = 67\% V_{DRM(max)};$ $T_j = 110 °C;$ exponential waveform; gate open circuit	30	60	70	-	V/µs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; \text{T}_{j} = 125 ^{\circ}\text{C};$ $I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 10V/\mu\text{s}; \text{ gate}$ open circuit	2.5	6.2	18	-	A/ms
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; \text{ T}_{j} = 125 \text{ °C};$ $I_{T(RMS)} = 16 \text{ A};$ $dV_{com}/dt = 0.1 \text{ V}/\mu\text{s}; \text{ gate}$ open circuit	12	20	50	-	A/ms

² Device does not trigger in the T2-, G+ quadrant.

BTA216 series D, E and F



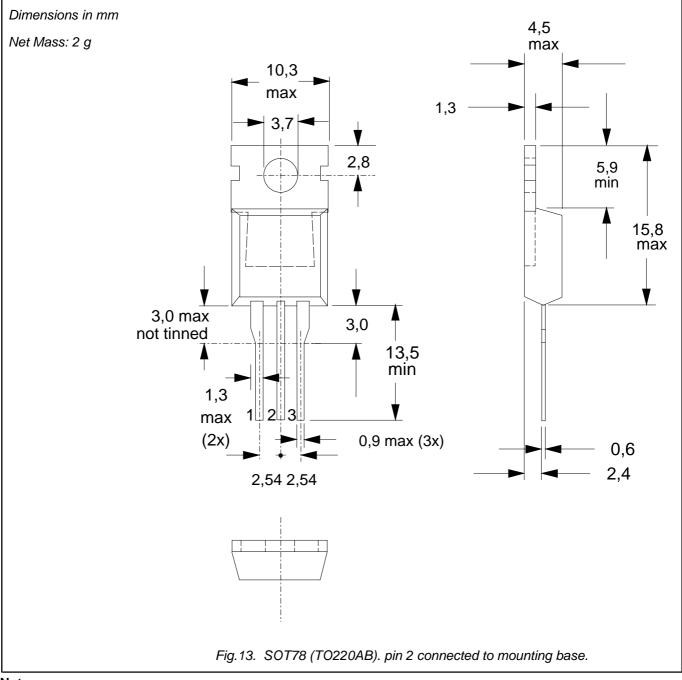
BTA216 series D, E and F

Three quadrant triacs guaranteed commutation

IT / A IGT(Tj) IGT(25°C) 50 Tj = 125 C Tj = 25 C 3 — T2+ G+ — T2+ Gtyp ma - T2- G-40 2.5 Vo = 1.195 V Rs = 0.018 Ohms 2 30 1.5 20 1 10 0.5 0└ 0 0 1.5 VT / V 150 0.5 2 2.5 3 -50 0 тј/°С 100 1 Fig.7. Normalised gate trigger current $I_{GT}(T_j)/I_{GT}(25^{\circ}C)$, versus junction temperature T_j . Fig.10. Typical and maximum on-state characteristic. 10 Eth j-mb (K/W) IL(Tj) IL(25°C) 3 25 1 bidirectional 2 0.1 1.5 → ^tp 1 0.01 0.5 0.001 – 10us 0└ -50 0.1ms 10ms 0.1s 1s 10s 50 Tj /℃ 1ms 0 100 150 tp/s Normalised latching current $I_L(T_{\underline{i}})/I_L(25^{\circ}C)$, Fig.11. Transient thermal impedance $Z_{th j-mb}$, versus Fig.8. versus junction temperature T_{i} pulse width $t_{\rm p}$ dlcom/dt (A/ms) IH(Tj) 100 3 IH(25°C F TYPE - E TYPE D TYPE 2.5 2 10 1.5 1 0.5 1 0└ -50 50 Tj /℃ 20 40 60 100 120 140 100 150 0 80 Tj/°C Fig.9. Normalised holding current $I_H(T_j)/I_H(25^{\circ}C)$, versus junction temperature T_j . Fig. 12. Minimum, critical rate of change of commutating current dI_{com}/dt versus junction temperature, $dV_{com}/dt = 10V/\mu s$.

BTA216 series D, E and F

MECHANICAL DATA



Notes

Refer to mounting instructions for SOT78 (TO220) envelopes.
Epoxy meets UL94 V0 at 1/8".

BTA216 series D, E and F

DEFINITIONS

DATA SHEET STATUS					
DATA SHEETPRODUCTSTATUS3STATUS4		DEFINITIONS			
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice			
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product			
Product data Production		This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A			

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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³ Please consult the most recently issued datasheet before initiating or completing a design.

⁴ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.